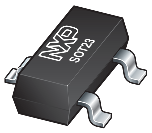


PMBFJ308; PMBFJ309; PMBFJ310

N-channel silicon field-effect transistors

Rev. 4 — 20 September 2011 Product data sheet

1. Product profile

1.1 General description

Symmetrical N-channel silicon junction field-effect transistors in a SOT23 package.

CAUTION

This device is sensitive to ElectroStatic Discharge (ESD). Therefore care should be taken during transport and handling.

1.2 Features and benefits

- Low noise
- Interchangeability of drain and source connections
- High gain.

1.3 Applications

- AM input stage in car radios
- VHF amplifiers
- Oscillators and mixers.

1.4 Quick reference data

Table 1. Quick reference data

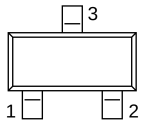
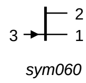
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage		-	-	±25	V
V_{GSoff}	gate-source cut-off voltage					
	PMBFJ308	V_{DS} = 10 V; I_D = 1 μA	−1	-	−6.5	V
	PMBFJ309	V_{DS} = 10 V; I_D = 1 μA	−1	-	−4	V
	PMBFJ310	V_{DS} = 10 V; I_D = 1 μA	−2	-	−6.5	V

Table 1. Quick reference data *…continued*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{DSS}	drain current					
	PMBFJ308	V_{GS} = 0 V; V_{DS} = 10 V	12	-	60	mA
	PMBFJ309	V_{GS} = 0 V; V_{DS} = 10 V	12	-	30	mA
	PMBFJ310	V_{GS} = 0 V; V_{DS} = 10 V	24	-	60	mA
P_{tot}	total power dissipation	up to T_{amb} = 25 °C	-	-	250	mW
$\lvert y_{fs} \rvert$	forward transfer admittance	V_{DS} = 10 V; I_D = 10 mA	10	-	-	mS

2. Pinning information

Table 2. Discrete pinning[1]

Pin	Description	Simplified outline	Symbol
1	source		
2	drain		
3	gate		

[1] Drain and source are interchangeable.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMBFJ308	-	plastic surface mounted package; 3 leads	SOT23
PMBFJ309			
PMBFJ310			

4. Marking

Table 4. Marking

Type number	Marking code[1]
PMBFJ308	48*
PMBFJ309	49*
PMBFJ310	50*

[1] * = p: Made in Hong Kong.

* = t: Made in Malaysia.

* = W: Made in China.

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage (DC)		-	±25	V
V_{GSO}	gate-source voltage	open drain	-	–25	V
V_{GDO}	gate-drain voltage	open source	-	–25	V
I_G	forward gate current (DC)		-	50	mA
P_{tot}	total power dissipation	up to T_{amb} = 25 °C	-	250	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		-	150	°C

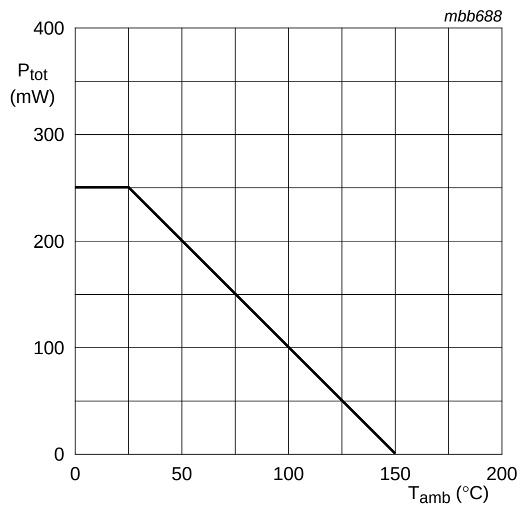


Fig 1. Power derating curve.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Typ	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient		[1]	500	K/W

[1] Device mounted on an FR4 printed-circuit board.

7. Static characteristics

Table 7. Static characteristics

T_j = 25 °C; unless otherwise specified.

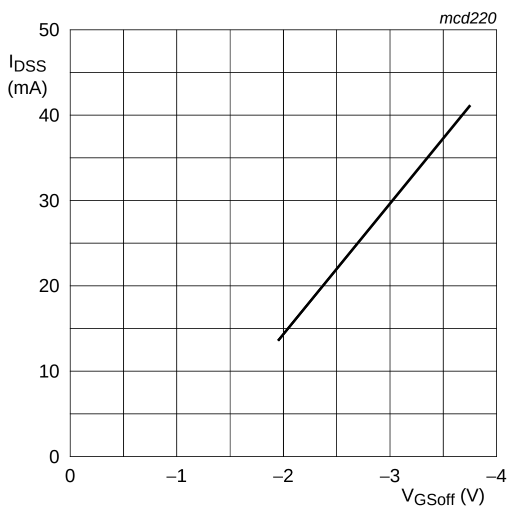
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)GSS}$	gate-source breakdown voltage	I_G = –1 μA; V_{DS} = 0 V	–25	-	-	V
V_{GSoff}	gate-source cut-off voltage					V
	PMBFJ308	I_D = 1 μA; V_{DS} = 10 V	–1	-	–6.5	V
	PMBFJ309	I_D = 1 μA; V_{DS} = 10 V	–1	-	–4	V
	PMBFJ310	I_D = 1 μA; V_{DS} = 10 V	–2	-	–6.5	V
V_{GSS}	gate-source forward voltage	I_G = 1 mA; V_{DS} = 0 V	-	-	1	V
I_{DSS}	drain-source leakage current					
	PMBFJ308	V_{GS} = 0 V; V_{DS} = 10 V	12	-	60	mA
	PMBFJ309	V_{GS} = 0 V; V_{DS} = 10 V	12	-	30	mA
	PMBFJ310	V_{GS} = 0 V; V_{DS} = 10 V	24	-	60	mA
I_{GSS}	gate-source leakage current	V_{GS} = –15 V; V_{DS} = 0 V	-	-	–1	nA
R_{DSon}	drain-source on-state resistance	V_{GS} = 0 V; V_{DS} = 100 mV	-	50	-	Ω
$\|y_{fs}\|$	forward transfer admittance	I_D = 10 mA; V_{DS} = 10 V	10	-	-	mS
$\|y_{os}\|$	common source output admittance	I_D = 10 mA; V_{DS} = 10 V	-	-	250	μS

8. Dynamic characteristics

Table 8. Dynamic characteristics

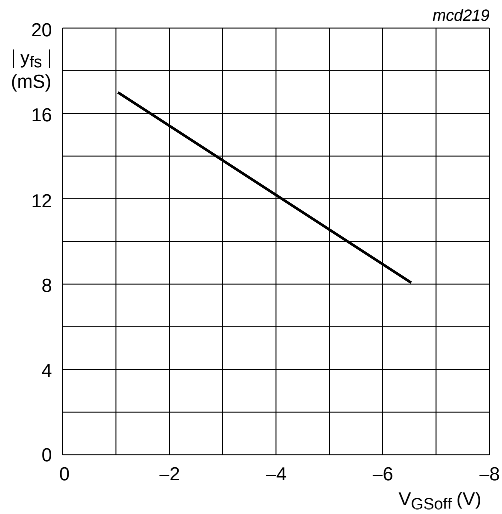
T_j = 25 °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C_{iss}	input capacitance	V_{DS} = 10 V				
		V_{GS} = –10 V; f = 1 MHz	-	3	5	pF
		V_{GS} = 0 V; T_{amb} = 25 °C	-	6	-	pF
C_{rss}	reverse transfer capacitance	V_{DS} = 0 V; V_{GS} = –10 V; f = 1 MHz	-	1.3	2.5	pF
g_{is}	input conductance	V_{DS} = 10 V; I_D = 10 mA				
		f = 100 MHz	-	200	-	μS
		f = 450 MHz	-	3	-	mS
g_{fs}	transfer conductance	V_{DS} = 10 V; I_D = 10 mA				
		f = 100 MHz	-	13	-	mS
		f = 450 MHz	-	12	-	mS
g_{rs}	reverse conductance	V_{DS} = 10 V; I_D = 10 mA				
		f = 100 MHz	-	–30	-	μS
		f = 450 MHz	-	–450	-	μS
g_{os}	output conductance	V_{DS} = 10 V; I_D = 10 mA				
		f = 100 MHz	-	150	-	μS
		f = 450 MHz	-	400	-	μS
V_n	equivalent input noise voltage	V_{DS} = 10 V; I_D = 10 mA; f = 100 Hz	-	6	-	nV/√Hz



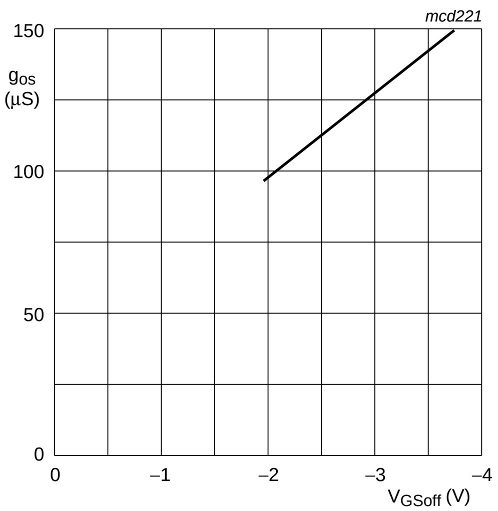
V_{DS} = 10 V; T_j = 25 °C.

Fig 2. Drain current as a function of gate-source cut-off voltage; typical values.



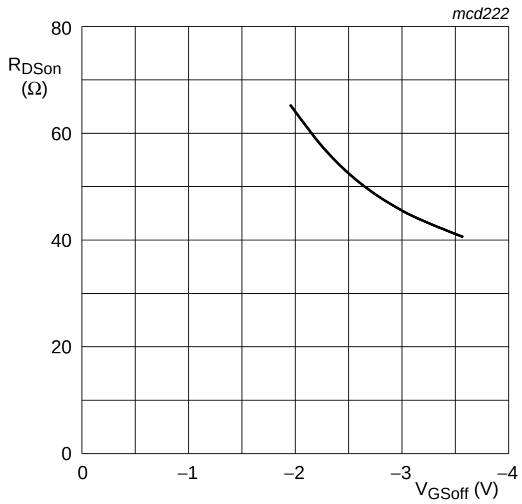
V_{DS} = 10 V; I_D = 10 mA; T_j = 25 °C.

Fig 3. Forward transfer admittance as a function of gate-source cut-off voltage; typical values.



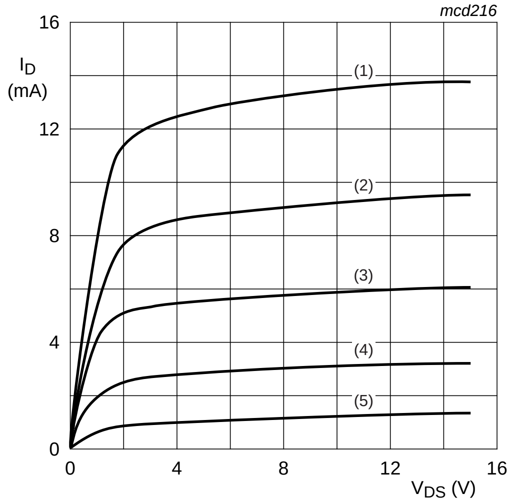
V_{DS} = 10 V; I_D = 10 mA; T_j = 25 °C.

Fig 4. Common-source output conductance as a function of gate-source cut-off voltage; typical values.



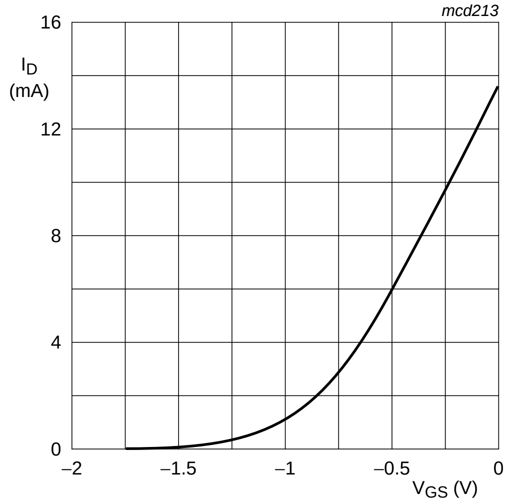
V_{DS} = 100 mV; V_{GS} = 0 V; T_j = 25 °C.

Fig 5. Drain-source on-state resistance as a function of gate-source cut-off voltage; typical values.



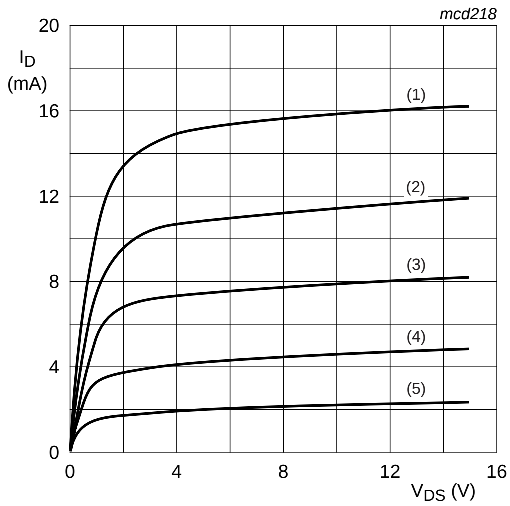
T_j = 25 °C.
(1) V_{GS} = 0 V.
(2) V_{GS} = –0.25 V.
(3) V_{GS} = –0.5 V.
(4) V_{GS} = –0.75 V.
(5) V_{GS} = –1 V.

Fig 6. Typical output characteristics; PMBFJ308.



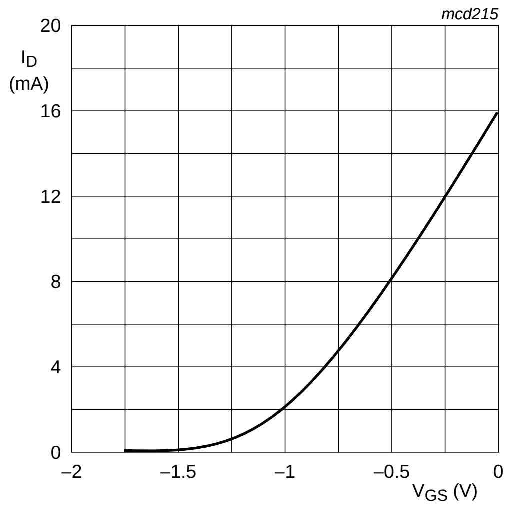
V_{DS} = 10 V; T_j = 25 °C.

Fig 7. Typical transfer characteristics; PMBFJ308.



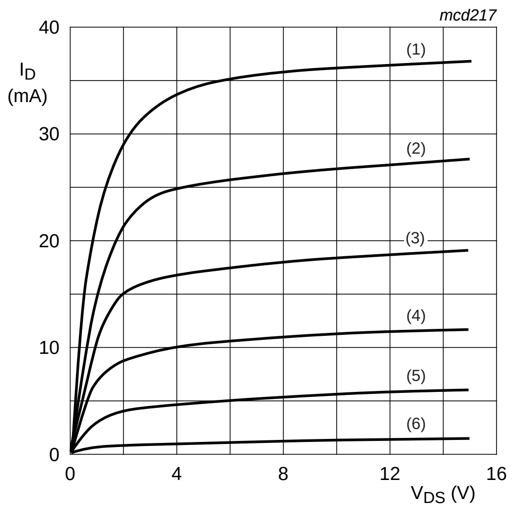
T_j = 25 °C.
(1) V_{GS} = 0 V.
(2) V_{GS} = –0.25 V.
(3) V_{GS} = –0.5 V.
(4) V_{GS} = –0.75 V.
(5) V_{GS} = –1 V.

Fig 8. Typical output characteristics; PMBFJ309.



V_{DS} = 10 V; T_j = 25 °C.

Fig 9. Typical transfer characteristics; PMBFJ309.



T_j = 25 °C.

(1) V_{GS} = 0 V.

(2) V_{GS} = −0.5 V.

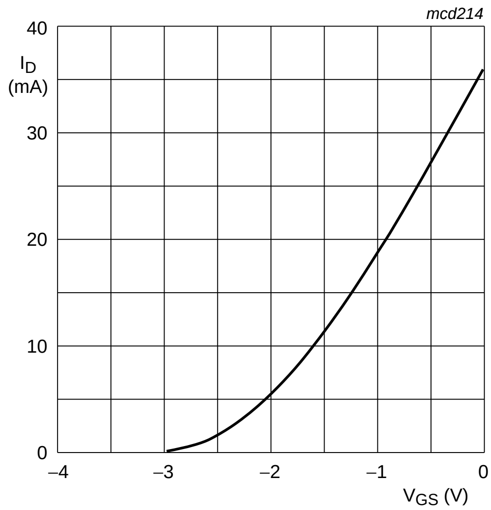
(3) V_{GS} = −1 V.

(4) V_{GS} = −1.5 V.

(5) V_{GS} = −2 V.

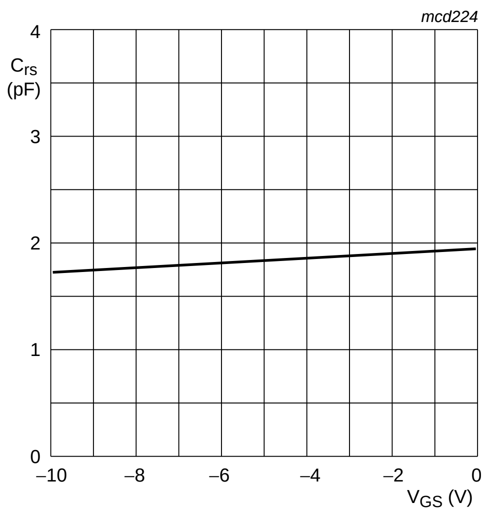
(6) V_{GS} = −2.5 V.

Fig 10. Typical output characteristics; PMBFJ310.



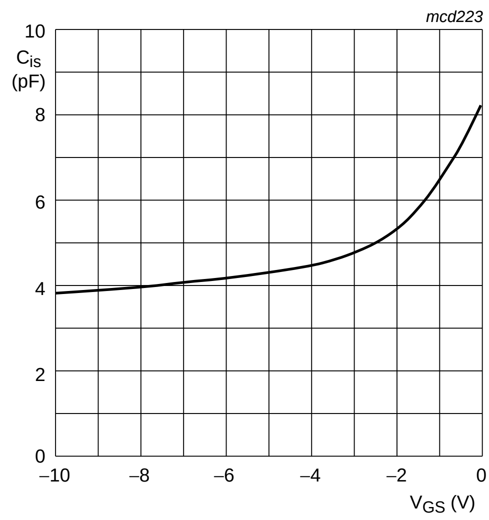
V_{DS} = 10 V; T_j = 25 °C.

Fig 11. Typical transfer characteristics; PMBFJ310.



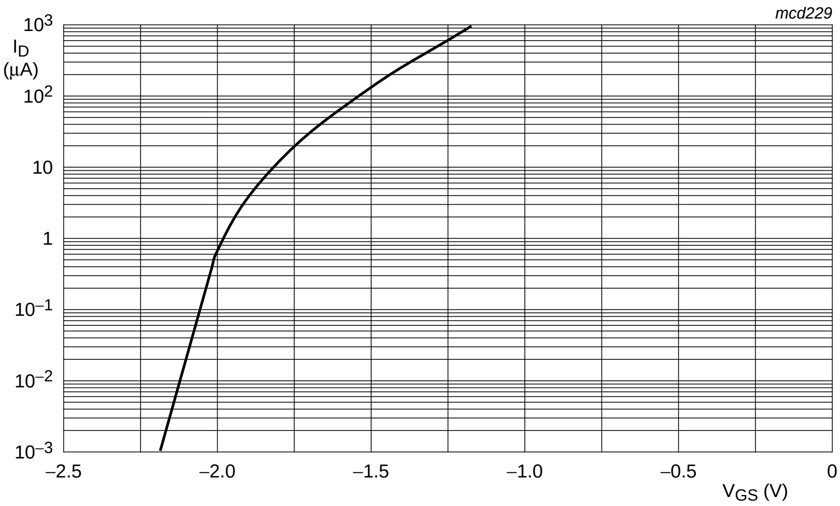
V_{DS} = 10 V; T_j = 25 °C.

Fig 12. Reverse transfer capacitance as a function of gate-source voltage; typical values.



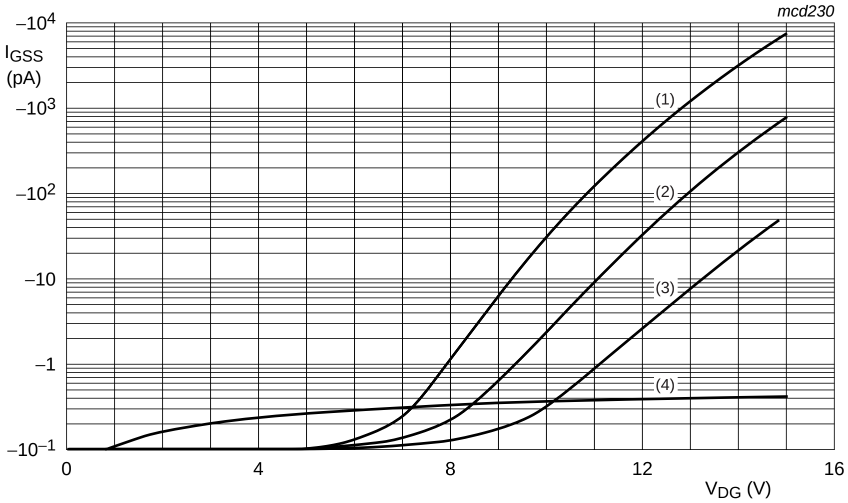
V_{DS} = 10 V; T_j = 25 °C.

Fig 13. Input capacitance as a function of gate-source voltage; typical values.



V_{DS} = 10 V; T_j = 25 °C.

Fig 14. Drain current as a function of gate-source voltage; typical values.



T_j = 25 °C.

(1) I_D = 10 mA.

(2) I_D = 1 mA.

(3) I_D = 100 μA.

(4) I_{GSS}.

Fig 15. Gate current as a function of drain-gate voltage; typical values.

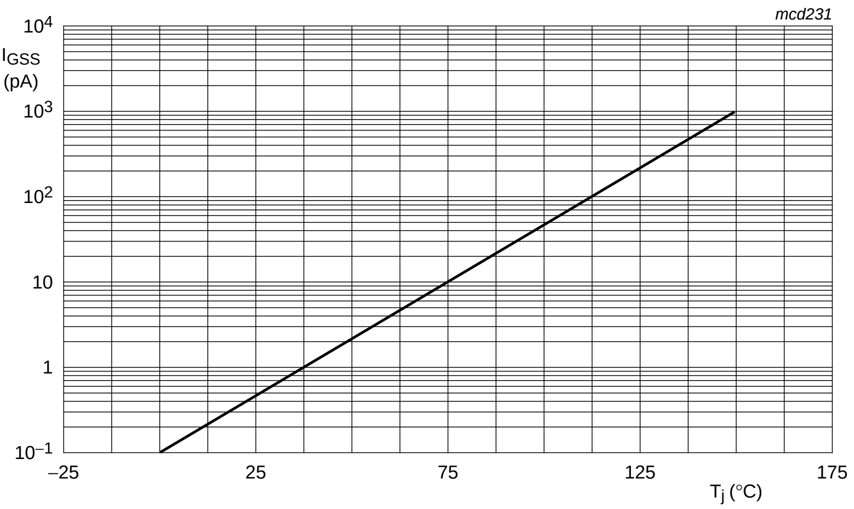
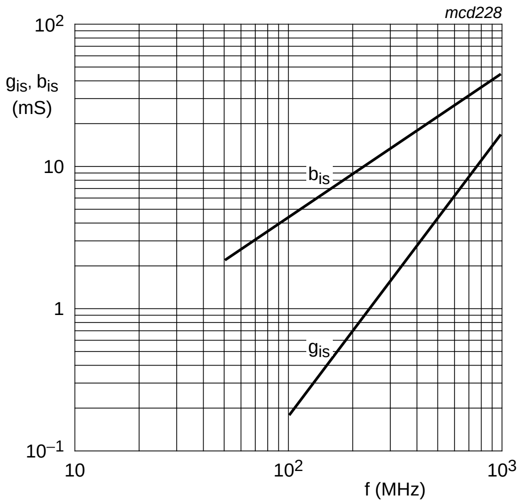
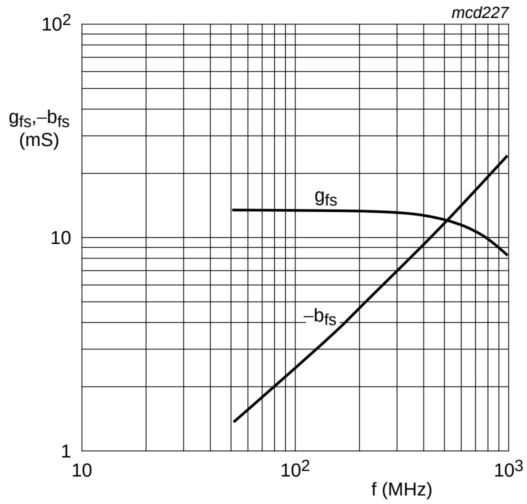


Fig 16. Gate current as a function of junction temperature; typical values.



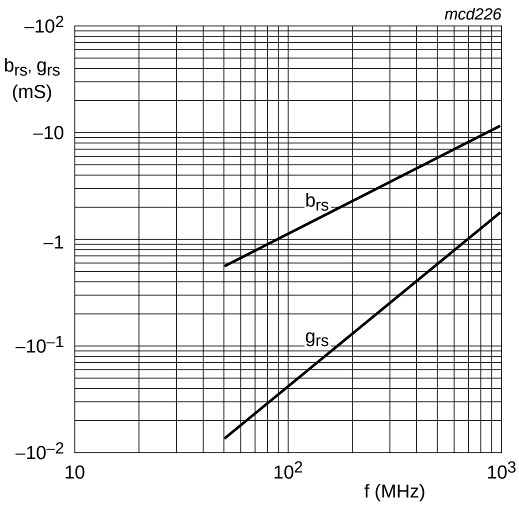
V_{DS} = 10 V; I_D = 10 mA; T_{amb} = 25 °C.

Fig 17. Input admittance; typical values.



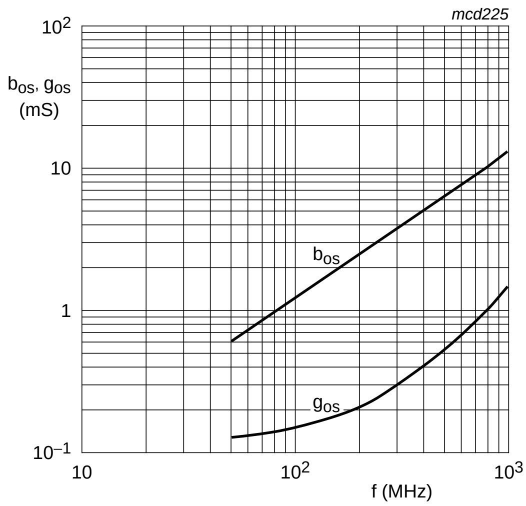
V_{DS} = 10 V; I_D = 10 mA; T_{amb} = 25 °C.

Fig 18. Forward transfer admittance; typical values.



V_{DS} = 10 V; I_D = 10 mA; T_{amb} = 25 °C.

Fig 19. Reverse transfer admittance; typical values.

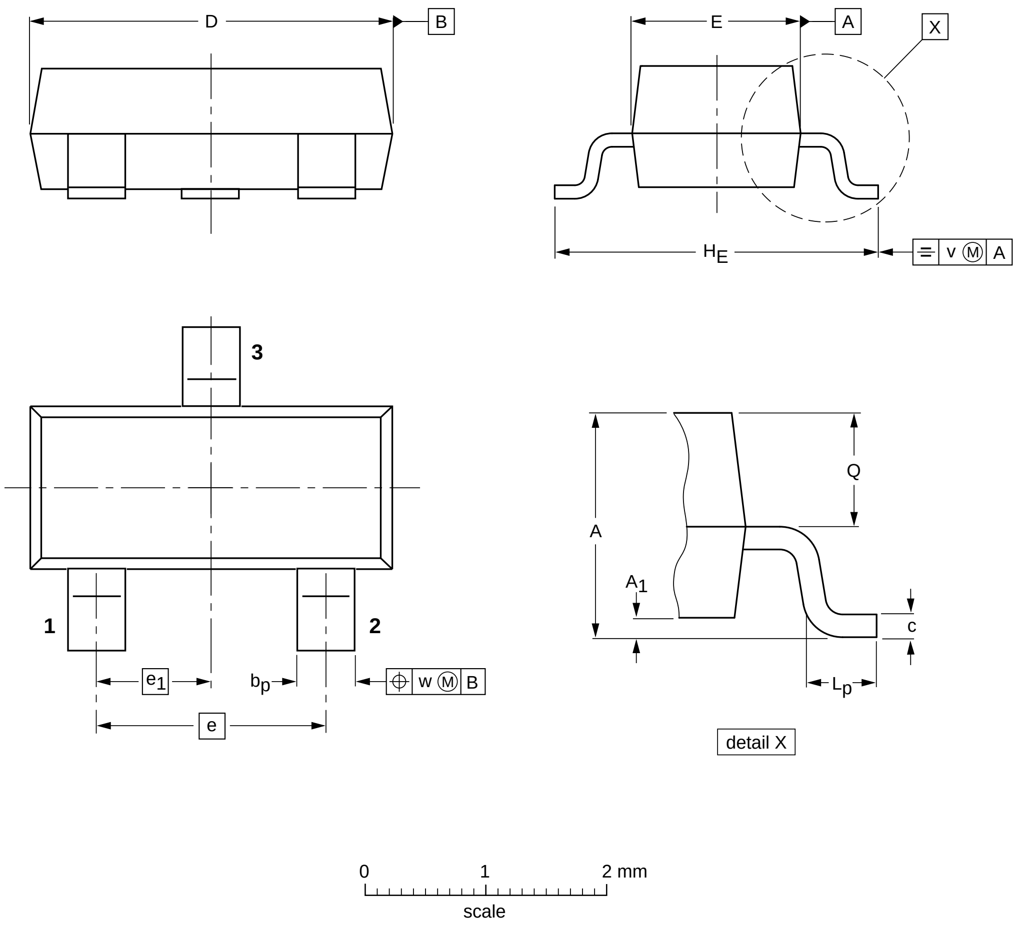


V_{DS} = 10 V; I_D = 10 mA; T_{amb} = 25 °C.

Fig 20. Output admittance; typical values.

9. Package outline

Plastic surface-mounted package; 3 leads **SOT23**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max.	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT23		TO-236AB				~~04-11-04~~ 06-03-16

Fig 21. Package outline.

10. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMBFJ308_309_310 v.4	20110920	Product data sheet	-	PMBFJ308_309_310 v.3
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Package outline drawings have been updated to the latest version.			
PMBFJ308_309_310 v.3 (9397 750 13403)	20040723	Product data sheet	-	PMBFJ308_309_310 v.2
PMBFJ308_309_310 v.2 (9397 750 01141)	19960911	Product specification	-	-

11. Legal information

11.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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12. Contact information

For more information, please visit: **http://www.nxp.com**

For sales office addresses, please send an email to: **salesaddresses@nxp.com**

13. Contents

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 20 September 2011

Document identifier: PMBFJ308_309_310